IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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pplication of:

Chad A. Cobbley et al.

Prior Application Serial No.: 10/672,750

Prior Application Filed:

September 25, 2003

Serial No.:

10/771,085

Filed:

February 03, 2004

For:

STACKED DIE MODULE AND

TECHNIQUES FOR FORMING A

STACKED DIE MODULE

Group Art Unit:

2813

Examiner:

Blum, David S.

Atty Docket: MICS:0078—3 (FLE)

(01-0752.03)

Mail Stop Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313

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Sir:

RESPONSE

In response to the Official Action mailed on September 08, 2004, Applicants respectfully request reconsideration of the above-identified application in view of the remarks set forth below.